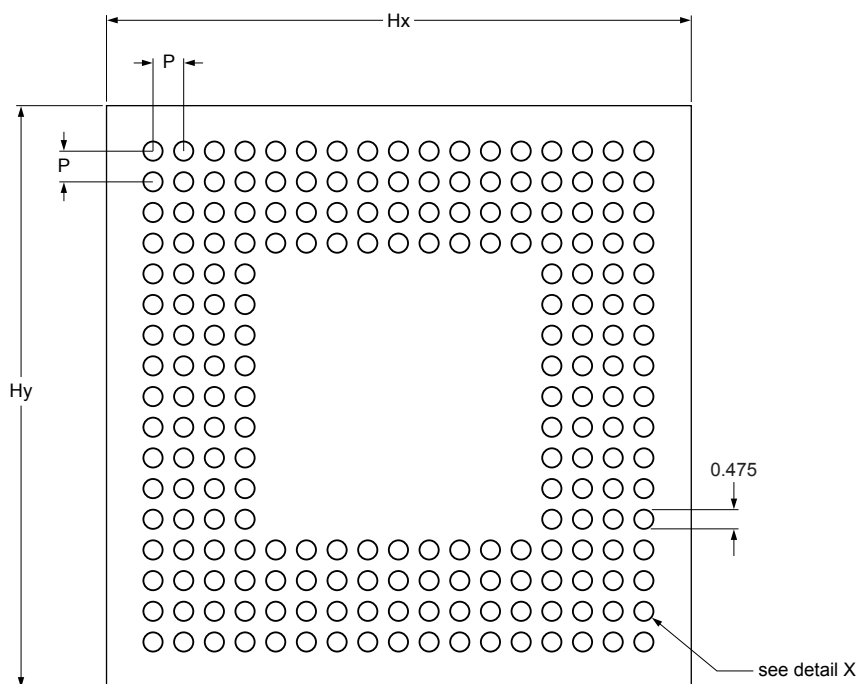



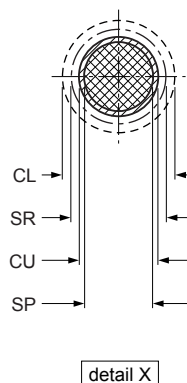


## Footprint information for reflow soldering of TFBGA208 package

SOT950-1



-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- \_\_\_\_\_ solder resist



Dimensions in mm

P	Hx	Hy	SP	CU	SR	CL
0.8	15.25	15.25	0.425	0.475	0.575	0.675

sot950-1\_fr